

Part Number: XZMEDGCBD45S

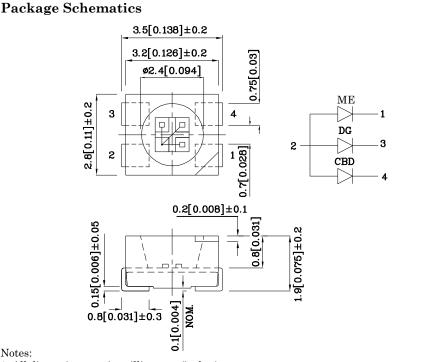
3.5x2.8mm PLCC4 SMD LED

Features

- Ideal for indication light on hand held products
- Long life and robust package
- Standard Package: 2000pcs/ Reel
- MSL (Moisture Sensitivity Level): 3
- RoHS compliant.



ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES



1. All dimensions are in millimeters (inches).

Notes:

2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.

3. Specifications are subject to change without notice.

(TA=95°C)		ME (AlGa InP)	DG (InGa N)	CBD (InGa N)UnitOperating Charactering (TA=25°C)		cteristics		ME (AlGaIn P)	DG (InGa N)	CBD (InGa N)	Unit		
Reverse Voltage	$V_{\rm R}$	5	5	5	V	Forward Voltage (Гур.) (I _F =20mA)	V_{F}	2	3.3	3.3	V	
Forward Current	$I_{\rm F}$	50	30	30	mA	Forward Voltage (I	Max.) (I _F =20mA)	$V_{\rm F}$	2.5	4.1	4	V	
Forward Current (Peak)						Reverse Current (Max.) (V _R =5V)	$I_{\rm R}$	10	50	50	uA		
1/10 Duty Cycle 0.1ms Pulse Width	$i_{\rm FS}$	195	150	150	mA	Wavelength of Pea Emission CIE127-2		λP	630*	515*	460*	nm	
Power Dissipation	P_D	125	123	120	mW	(I _F =20mA)		A1	050	010	400		
Operating Temperature	$T_{\rm A}$	40			°C	Wavelength of Dominant Emission CIE127-2007*(Typ.) (I _F =20mA)		λD	621*	525*	465*	nm	
Storage Temperature	Tstg		-40 ~ +85										
Electrostatic Discharge Threshold (HBM)		-	450	250	V	Spectral Line Full At Half-Maximum (I _F =20mA)		$ riangle \lambda$	20	30	25	nm	
						Capacitance (Typ.) (V _F =0V, f=1MHz)		С	25	45	100	pF	
Part Number		Emitting Color		Emitting Material		Lens-color Lens-color		7*	CIEI	elength 127-2007* nm AP	An	Viewing Angle 20 1/2	
							min. t	typ.					
Red		Red		AlGa	InP		120* 2	218*	6	30*			

	Red	AlGaInP		120*	218*	630*	_
XZMEDGCBD45S	Green	InGaN	Water Clear	400*	497*	515*	120°
	Blue	InGaN		55*	98*	460*	

*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

Mar 06,2014

XDSB7192 V2-Z Layout: Maggie L.

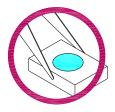


3.5x2.8mm PLCC4 SMD LED

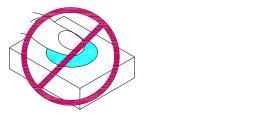
Handling Precautions

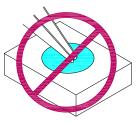
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force. As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.

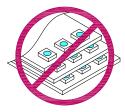


2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.

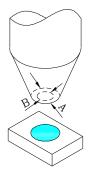




3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.

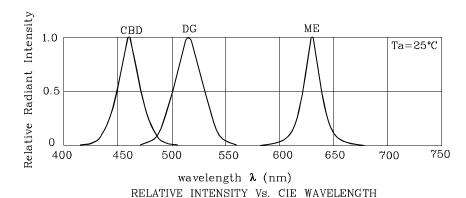


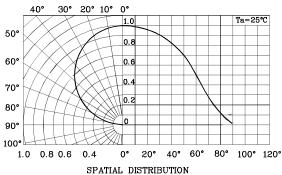
4.1. The inner diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks.4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



5. As silicone encapsulation is permeable to gases, some corrosive substances such as H_2S might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

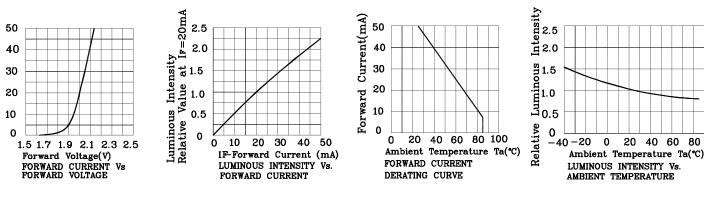
3.5x2.8mm PLCC4 SMD LED



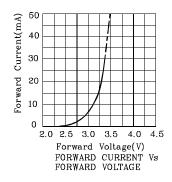


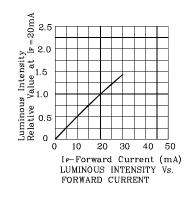
♦ ME

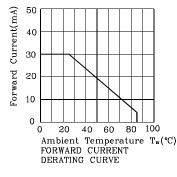
Forward Current(mA)

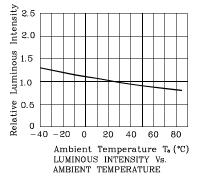


♦ DG

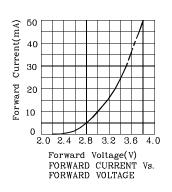


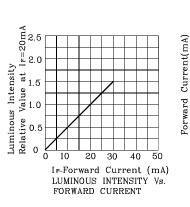


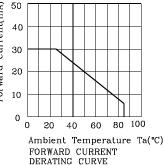


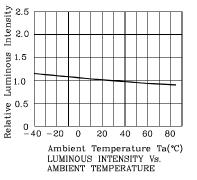


CBD









XDSB7192 V2-Z Layout: Maggie L.



300 (°C)

250

200

150

100

50

Notes

Temperature

LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)

4°C/s

80~120

100

high temperatures conditions

Tim

Recommended reflow temperature: 145°C-260°C
Do not put stress to the epoxy resin during

150

Maximum soldering temperature should not exceed 260°C

200

150~180°C

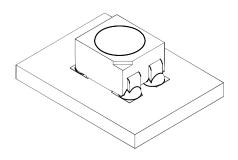
4℃/s max

10 8

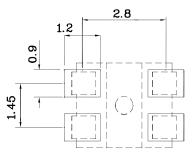
C/s r

250

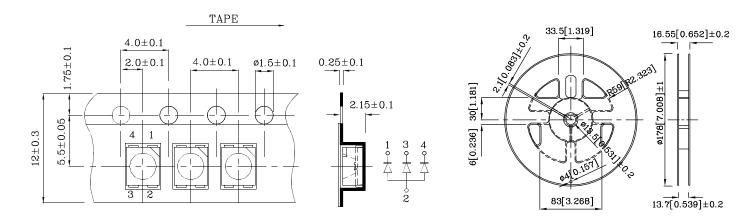
300 (sec) ✤ The device has a single mounting surface. The device must be mounted according to the specifications.



Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



Reel Dimension



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm

2. Luminous intensity / luminous flux: +/-15%

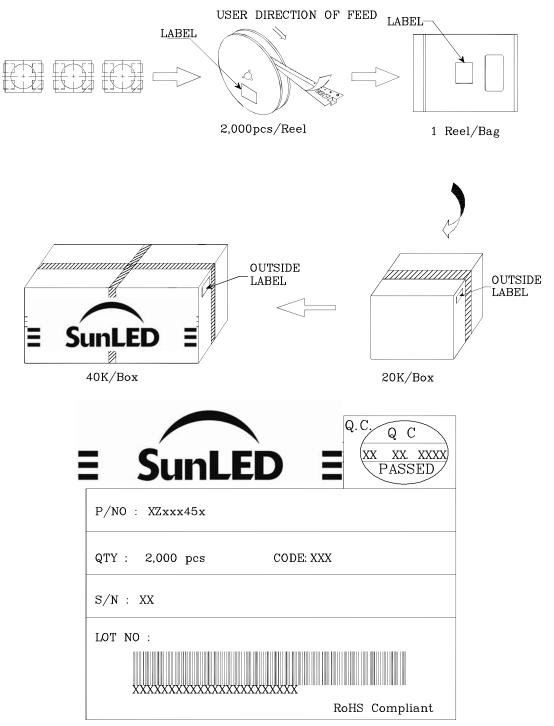
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

Tape Specification (Units : mm)



PACKING & LABEL SPECIFICATIONS



TERMS OF USE

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- 2. Contents within this document are subject to improvement and enhancement changes without notice.
- 3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet.
- User accepts full risk and responsibility when operating the product(s) beyond their intended specifications.
- 4. The product(s) described in this document are intended for electronic applications in which a person's life is not reliant upon the LED. Please
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- 6. Additional technical notes are available at http://www.SunLEDusa.com/TechnicalNotes.asp